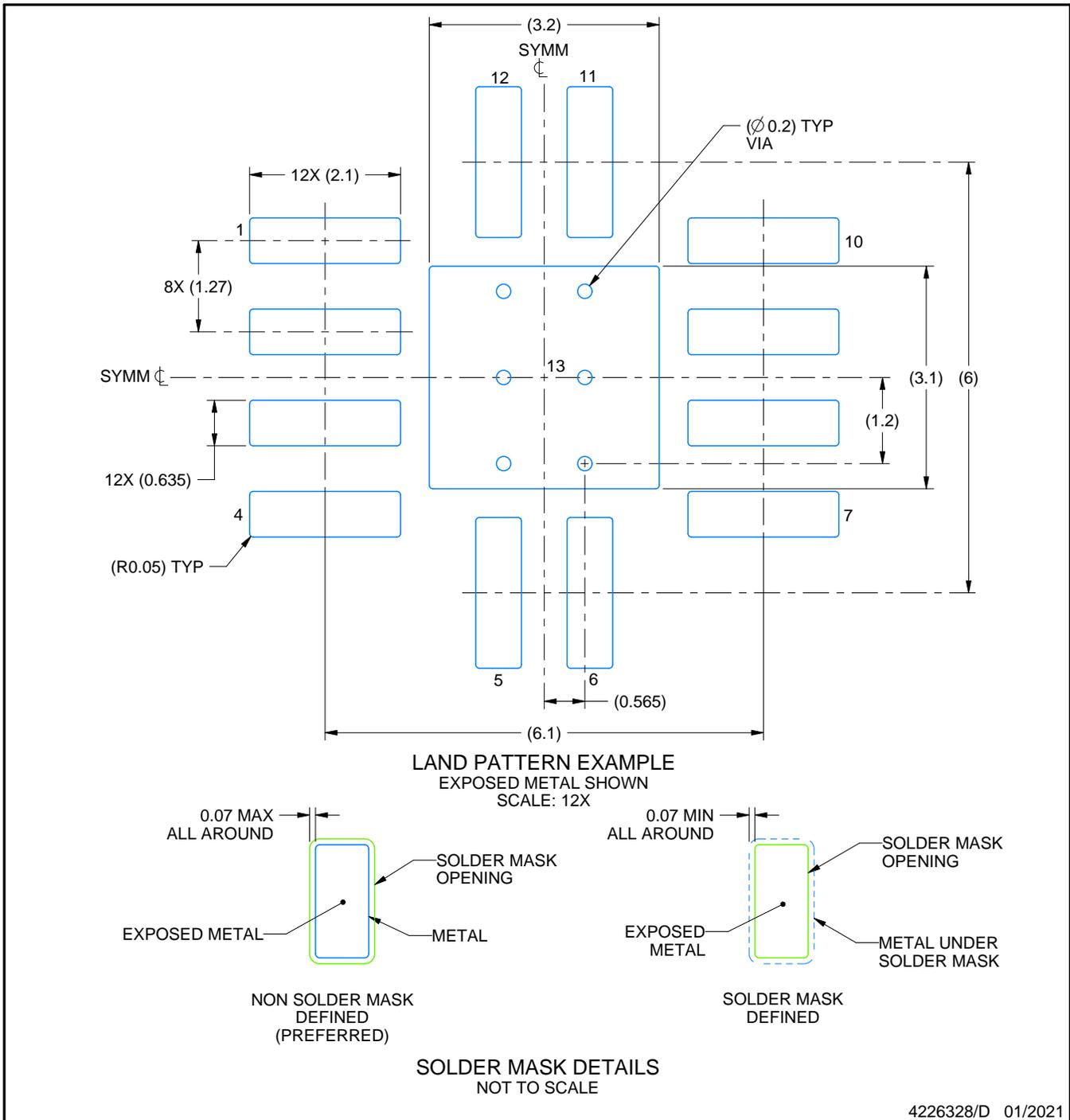


EXAMPLE BOARD LAYOUT

FFM0012A

LCCC - 1.78 mm max height

LEADLESS CERAMIC CHIP CARRIER



NOTES: (continued)

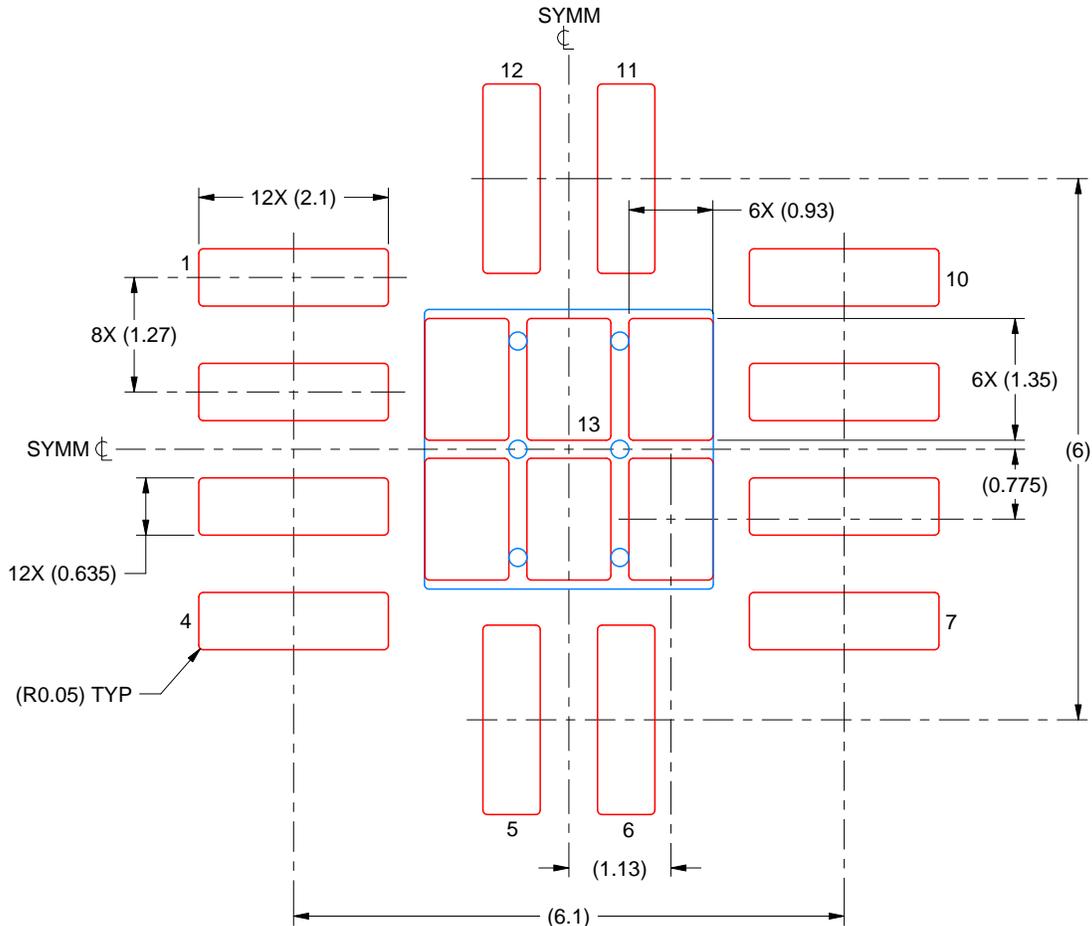
- This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/sluea271).
- Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

EXAMPLE STENCIL DESIGN

FFM0012A

LCCC - 1.78 mm max height

LEADLESS CERAMIC CHIP CARRIER



SOLDER PASTE EXAMPLE
 BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD 13:
 76% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
 SCALE: 12X

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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